



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS5030-2EKA		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001130774						
<b>Package</b>		PG-DSO-14-40		<b>Weight*</b>		149.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.425	2.29	2.29	22853	22853
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		464	
	non noble metal	iron	7439-89-6	1.392	0.93		9288	
wire	non noble metal	copper	7440-50-8	56.512	37.71	38.70	377127	386995
	non noble metal	copper	7440-50-8	0.955	0.64	0.64	6373	6373
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1119
	plastics	epoxy resin	-	7.711	5.15		51462	
	inorganic material	silicondioxide	60676-86-0	75.941	50.66	55.92	506788	559369
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8183	8183
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9460	9460
glue	plastics	epoxy resin	-	0.177	0.12		1184	
	noble metal	silver	7440-22-4	0.837	0.56	0.68	5583	6767
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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